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RRD-B30M115/Printed in U. S. A.

lf Militar please	lute Maxim ry/Aerospace sp contact the Na vistributors for av	ecified	d device Semic	es are required, onductor Sales	Power Dis (Notes)		n	H Pack 670 n	°.		N Packag 670 mW		
(Note 8)					T _i max			150°	С		115°C		
Supply Voltage			F411A LF411 ±22V ±18V		θ _j A			62°C/W (Still Air) °C/W (400 LF/min			120°C/W		
	al Input Voltage	±	38V	\pm 30V					Flow)				
Input Voltage Range (Note 1)		±	19V	$ heta_j C \\ \pm 15 V ext{Operating}$		Temp.		20°C.	/W				
	hort Circuit				Range			(Note 3)			(Note 3)		
Duratio	n	Cont	inuous	Continuous	Storage T Range	emp.	-65	5°C≤T₄	≤150°	C -6	5°C≤T _A ≤	150°C	
					Lead Terr								
					(Solder		sec.)	260°	С		260°C		
					ESD Tole	rance				Rating to	o be detern	nined.	
DC EI	ectrical Ch	arac	cteris	tics (Note 4)									
Symbol	Parameter			Conditions		LF411A				LF411			
Cymbol	i arameter			Conditions		Min		Max	Min	Тур	Max	Units	
V _{OS}							Тур	max		i yp	IVIAA		
•05	Input Offset Volta	age	R _S =10	kΩ, T _A =25°C			0.3	0.5		0.8	2.0	mV	
$\Delta V_{OS} / \Delta T$	Input Offset Volta Average TC of In Offset Voltage			kΩ, T _A =25°C kΩ (Note 5)								mV μV/°C	
	Average TC of In	put	$R_S = 10$ $V_S = \pm 1$	kΩ (Note 5) 5V	Tj=25℃		0.3	0.5		0.8	2.0 20		
$\Delta V_{OS} / \Delta T$	Average TC of In Offset Voltage	put	R _S =10	kΩ (Note 5) 5V	T _j =25°C T _j =70°C		0.3 7	0.5 10		0.8 7	2.0 20 (Note 5)	μV/°C	
$\Delta V_{OS} / \Delta T$	Average TC of In Offset Voltage	put	$R_S = 10$ $V_S = \pm 1$	kΩ (Note 5) 5V	1		0.3 7	0.5 10 100		0.8 7	2.0 20 (Note 5) 100	μV/°C pA	
$\Delta V_{OS} / \Delta T$	Average TC of In Offset Voltage	put ent	$R_S = 10$ $V_S = \pm 1$ (Notes 4 $V_S = \pm 1$	kΩ (Note 5) 5V I, 6) 5V	T _j =70°C		0.3 7	0.5 10 100 2		0.8 7	2.0 20 (Note 5) 100 2	μV/°C pA nA	
ΔV _{OS} /ΔT	Average TC of In Offset Voltage Input Offset Curre	put ent	$R_S = 10$ $V_S = \pm 1$ (Notes 4	kΩ (Note 5) 5V I, 6) 5V	$T_j = 70^{\circ}C$ $T_j = 125^{\circ}C$		0.3 7 25	0.5 10 100 2 25		0.8 7 25	2.0 20 (Note 5) 100 2 25	μV/°C pA nA nA	
ΔV _{OS} /ΔT	Average TC of In Offset Voltage Input Offset Curre	put ent	$R_S = 10$ $V_S = \pm 1$ (Notes 4 $V_S = \pm 1$	kΩ (Note 5) 5V I, 6) 5V	$T_j = 70^{\circ}C$ $T_j = 125^{\circ}C$ $T_j = 25^{\circ}C$		0.3 7 25	0.5 10 100 2 25 200		0.8 7 25	2.0 20 (Note 5) 100 2 25 200	μV/°C pA nA nA pA	
ΔV _{OS} /ΔT	Average TC of In Offset Voltage Input Offset Curre	ent nt	$R_S = 10$ $V_S = \pm 1$ (Notes 4 $V_S = \pm 1$	kΩ (Note 5) 15V I, 6) 5V I, 6)	$T_{j} = 70^{\circ}C$ $T_{j} = 125^{\circ}C$ $T_{j} = 25^{\circ}C$ $T_{j} = 70^{\circ}C$		0.3 7 25	0.5 10 100 2 25 200 4		0.8 7 25	2.0 20 (Note 5) 100 2 25 200 4	μV/°C pA nA nA pA nA	
ΔV _{OS} /ΔT los l _B	Average TC of In Offset Voltage Input Offset Curre Input Bias Curren	ent nt	$R_{S} = 10$ $V_{S} = \pm 1$ (Notes 4 $V_{S} = \pm 1$ (Notes 4 $T_{j} = 25^{\circ}$ $V_{S} = \pm 1$	kΩ (Note 5) 15V I, 6) 5V I, 6)	$T_{j} = 70^{\circ}C$ $T_{j} = 125^{\circ}C$ $T_{j} = 25^{\circ}C$ $T_{j} = 70^{\circ}C$	50	0.3 7 25 50	0.5 10 100 2 25 200 4	25	0.8 7 25 50	2.0 20 (Note 5) 100 2 25 200 4	μV/°C pA nA nA pA nA nA	

	Over Temperature	25	200		15	200
Output Voltage Swing	$V_{S} = \pm 15V, R_{L} = 10k$	±12	±13.5		±12	±13.5
Input Common-Mode		±16	+ 19.5		±11	+14.5
Voltage Range			-16.5			-11.5
Common-Mode Rejection Ratio	R _S ≤10k	80	100		70	100
Supply Voltage Rejection Ratio	(Note 7)	80	100		70	100
Supply Current			1.8	2.8		1.8
	Input Common-Mode Voltage Range Common-Mode Rejection Ratio Supply Voltage Rejection Ratio	$\begin{tabular}{ c c c c } \hline Output Voltage Swing & V_S = \pm 15V, R_L = 10k \\ \hline Input Common-Mode \\ Voltage Range & \\ \hline Common-Mode \\ Rejection Ratio & \\ \hline Supply Voltage \\ Rejection Ratio & \\ \hline \end{array} \end{tabular}$	$\begin{array}{c c} Output Voltage Swing} & V_S = \pm 15V, R_L = 10k & \pm 12 \\ Input Common-Mode \\ Voltage Range & & \\ \hline \\ \hline \\ Common-Mode \\ Rejection Ratio & \\ \hline \\ Supply Voltage \\ Rejection Ratio & \\ \hline \\ \hline \\ \hline \\ \hline \\ 80 & \\ \hline \\ 80 & \\ \hline \\ \hline \\ 80 & \\ \hline \\$	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $

AC Electrical Characteristics (Note 4)

Parameter	Conditions	LF411A			LF411			Units
T arameter	Conditions	Min	Тур	Мах	Min	Тур	Мах	onito
Slew Rate	$V_S\!=\pm15V,T_A\!=\!25^\circ\!C$	10	15		8	15		V/µs
Gain-Bandwidth Product	$V_S = \pm 15V, T_A = 25^{\circ}C$	3	4		2.7	4		MHz
Equivalent Input Noise Voltage	$T_A = 25^{\circ}C, R_S = 100\Omega,$ f = 1 kHz	-	25			25		nV⁄i∕ √Hz
Equivalent Input Noise Current	$T_A = 25^{\circ}C$, f = 1 kHz		0.01			0.01		pA∕⁄ √Hz
	Gain-Bandwidth Product Equivalent Input Noise Voltage	Slew Rate $V_S = \pm 15V, T_A = 25^{\circ}C$ Gain-Bandwidth Product $V_S = \pm 15V, T_A = 25^{\circ}C$ Equivalent Input Noise Voltage $T_A = 25^{\circ}C, R_S = 100\Omega, f = 1 \text{ kHz}$	$\begin{tabular}{ c c c c c } \hline Min \\ \hline Slew Rate & V_S = \pm 15V, T_A = 25^\circ C & 10 \\ \hline Gain-Bandwidth Product & V_S = \pm 15V, T_A = 25^\circ C & 3 \\ \hline Equivalent Input Noise Voltage & T_A = 25^\circ C, R_S = 100\Omega, \\ f = 1 \ kHz & Hz & Hz \\ \hline \end{array}$	ParameterConditionsMinTypSlew Rate $V_S = \pm 15V, T_A = 25^{\circ}C$ 1015Gain-Bandwidth Product $V_S = \pm 15V, T_A = 25^{\circ}C$ 34Equivalent Input Noise Voltage $T_A = 25^{\circ}C, R_S = 100\Omega, f = 1 \text{ kHz}$ 25	ParameterConditionsMinTypMaxSlew Rate $V_S = \pm 15V, T_A = 25^{\circ}C$ 1015Gain-Bandwidth Product $V_S = \pm 15V, T_A = 25^{\circ}C$ 34Equivalent Input Noise Voltage $T_A = 25^{\circ}C, R_S = 100\Omega, f = 1 \text{ kHz}$ 25	ParameterConditionsMinTypMaxMinSlew Rate $V_S = \pm 15V, T_A = 25^{\circ}C$ 10158Gain-Bandwidth Product $V_S = \pm 15V, T_A = 25^{\circ}C$ 342.7Equivalent Input Noise Voltage $T_A = 25^{\circ}C, R_S = 100\Omega, f = 1 \text{ kHz}$ 2525	ParameterConditionsMinTypMaxMinTypSlew Rate $V_S = \pm 15V, T_A = 25^{\circ}C$ 1015815Gain-Bandwidth Product $V_S = \pm 15V, T_A = 25^{\circ}C$ 342.74Equivalent Input Noise Voltage $T_A = 25^{\circ}C, R_S = 100\Omega,$ f = 1 kHz252525	ParameterConditionsImage: Non-Image: Non-I

V/mV

V V V

dB

dB

mA

3.4

Note 1: Unless otherwise specified the absolute maximum negative input voltage is equal to the negative power supply voltage.

Note 2: For operating at elevated temperature, these devices must be derated based on a thermal resistance of $\theta_i A$.

Note 3: These devices are available in both the commercial temperature range $0^{\circ}C \le T_A \le 70^{\circ}C$ and the military temperature range $-55^{\circ}C \le T_A \le 125^{\circ}C$. The temperature range is designated by the position just before the package type in the device number. A "C" indicates the commercial temperature range and an "M" indicates the military temperature range. The military temperature range is available in "H" package only.

Note 4: Unless otherwise specified, the specifications apply over the full temperature range and for $V_S = \pm 20V$ for the LF411A and for $V_S = \pm 15V$ for the LF411. V_{OS} , I_B , and I_{OS} are measured at $V_{CM} = 0$.

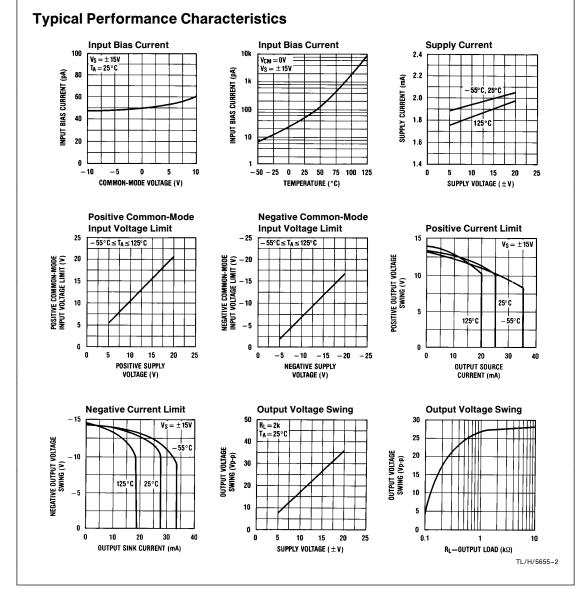
Note 5: The LF411A is 100% tested to this specification. The LF411 is sample tested to insure at least 90% of the units meet this specification.

Note 6: The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature, T_j . Due to limited production test time, the input bias currents measured are correlated to junction temperature. In normal operation the junction temperature rises above the ambient temperature as a result of internal power dissipation, P_D . $T_j = T_A + \theta_{jA} P_D$ where θ_{jA} is the thermal resistance from junction to ambient. Use of a heat sink is recommended if input bias current is to be kept to a minimum.

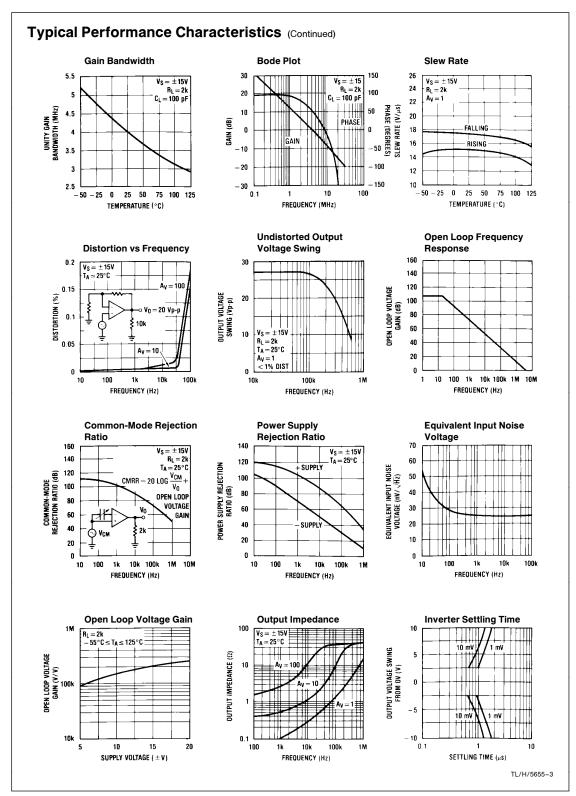
Note 7: Supply voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously in accordance with common practice, from ±15V to ±5V for the LF411 and from ±20V to ±5V for the LF411A.

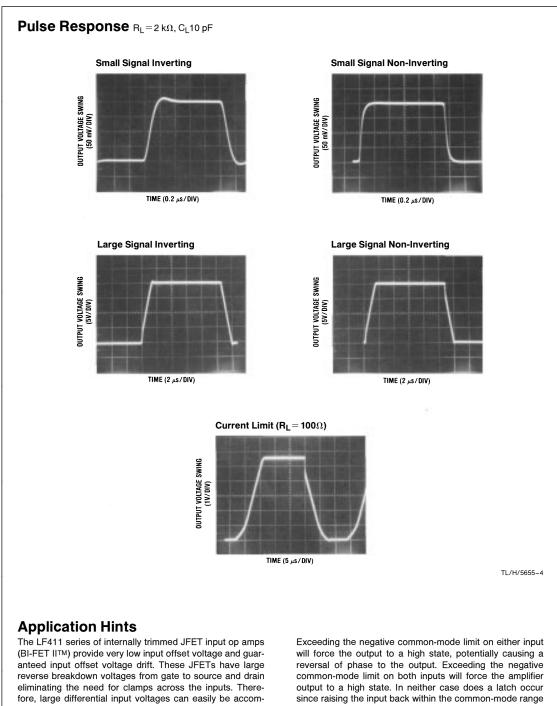
Note 8: RETS 411X for LF411MH and LF411MJ military specifications.

Note 9: Max. Power Dissipation is defined by the package characteristics. Operating the part near the Max. Power Dissipation may cause the part to operate outside guaranteed limits.



3





modated without a large increase in input current. The maximum differential input voltage is independent of the supply voltages. However, neither of the input voltages should be allowed to exceed the negative supply as this will cause large currents to flow which can result in a destroyed unit. again puts the input stage and thus the amplifier in a normal operating mode. Exceeding the positive common-mode limit on a single input will not change the phase of the output; however, if both inputs exceed the limit, the output of the amplifier may be forced to a high state.

Application Hints (Continued)

The amplifier will operate with a common-mode input voltage equal to the positive supply; however, the gain bandwidth and slew rate may be decreased in this condition. When the negative common-mode voltage swings to within 3V of the negative supply, an increase in input offset voltage may occur.

The LF411 is biased by a zener reference which allows normal circuit operation on $\pm 4.5 \text{V}$ power supplies. Supply voltages less than these may result in lower gain bandwidth and slew rate.

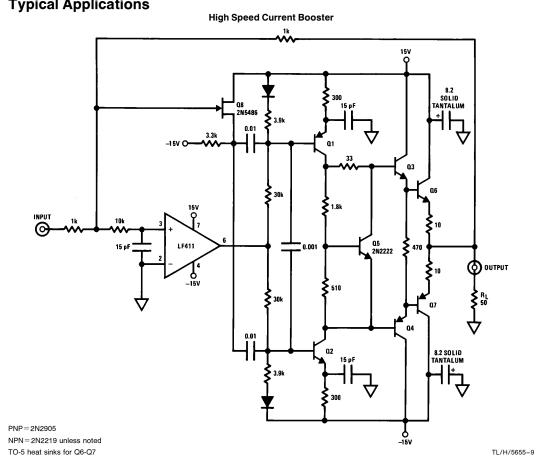
The LF411 will drive a 2 k Ω load resistance to $\,\pm\,$ 10V over the full temperature range. If the amplifier is forced to drive heavier load currents, however, an increase in input offset voltage may occur on the negative voltage swing and finally reach an active current limit on both positive and negative swinas.

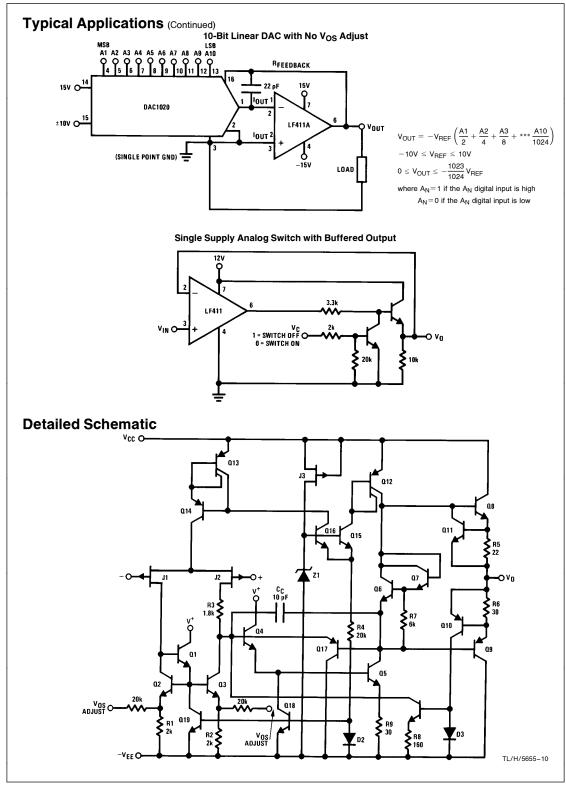
Precautions should be taken to ensure that the power supply for the integrated circuit never becomes reversed in polarity or that the unit is not inadvertently installed backwards in a socket as an unlimited current surge through the resulting forward diode within the IC could cause fusing of the internal conductors and result in a destroyed unit.

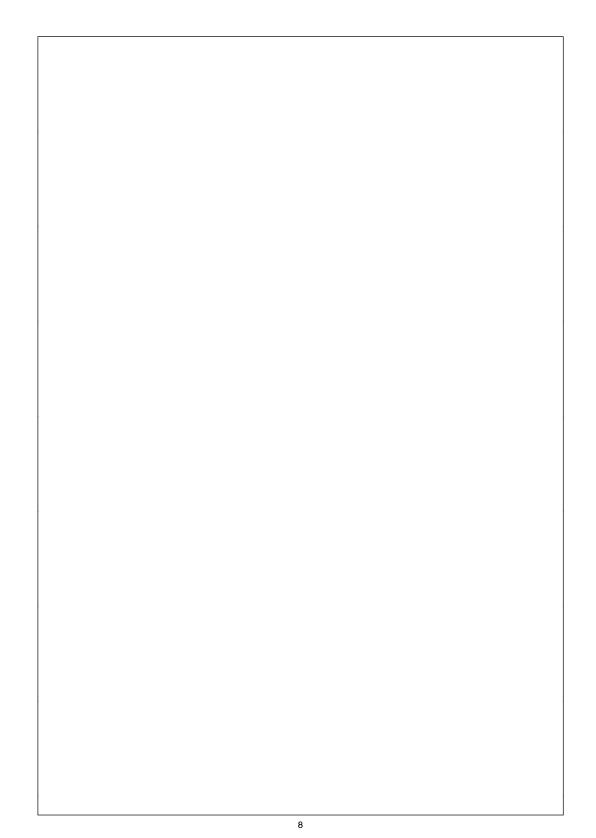
Typical Applications

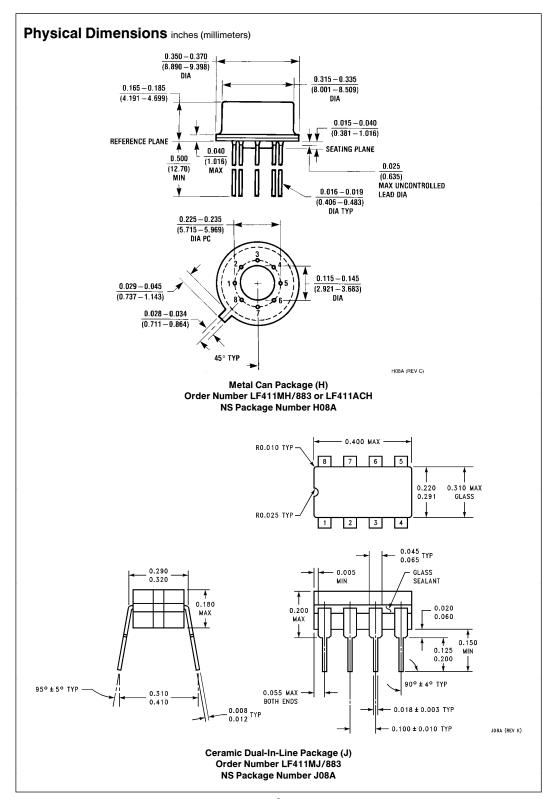
As with most amplifiers, care should be taken with lead dress, component placement and supply decoupling in order to ensure stability. For example, resistors from the output to an input should be placed with the body close to the input to minimize "pick-up" and maximize the frequency of the feedback pole by minimizing the capacitance from the input to around.

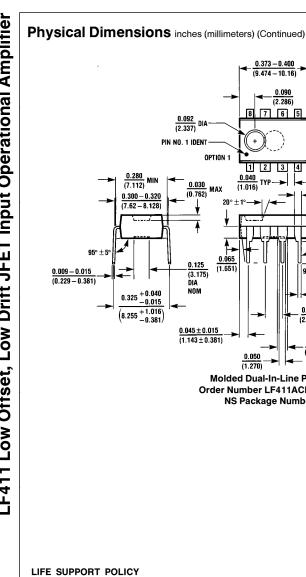
A feedback pole is created when the feedback around any amplifier is resistive. The parallel resistance and capacitance from the input of the device (usually the inverting input) to AC ground set the frequency of the pole. In many instances the frequency of this pole is much greater than the expected 3 dB frequency of the closed loop gain and consequently there is negligible effect on stability margin. However, if the feedback pole is less than approximately 6 times the expected 3 dB frequency, a lead capacitor should be placed from the output to the input of the op amp. The value of the added capacitor should be such that the RC time constant of this capacitor and the resistance it parallels is greater than or equal to the original feedback pole time constant.



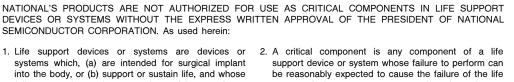








to the user.



failure to perform, when properly used in accordance support device or system, or to affect its safety or with instructions for use provided in the labeling, can effectiveness. be reasonably expected to result in a significant injury

Rational Semiconductor Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018	National Semiconductor Europe Fax: (+49) 0.180-530 85 86 Email: cnjwge@tevm2.nsc.com Deutsch Tei: (+49) 0.180-530 85 85 English Tei: (+49) 0.180-532 78 32 Français Tei: (+49) 0.180-532 78 32 Italiano Tei: (+49) 0.180-534 16 80	National Semiconductor Hong Kong Ltd. 13th Floor, Straight Block, Ocean Centre, 5 Canton Rd. Tsimshatsui, Kowloon Hong Kong Tei: (852) 2737-1600 Fax: (852) 2736-9960	National Semiconductor Japan Ltd. Tei: 81-043-299-2309 Fax: 81-043-299-2408
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0.373 - 0.400(9.474 - 10.16) 0.090 8 7 6 5

1 2 3 4

0.040 (1.016) TYP

<u>0.050</u> (1.270)

Molded Dual-In-Line Package (N) Order Number LF411ACN or LF411CN NS Package Number N08E

+

 $\underline{0.250\pm0.005}$

 (6.35 ± 0.127)

¥

0.039 (0.991)

90[°] ± 4

TYP

 0.100 ± 0.010

(2.540±0.254)

0.060 (1.524)

 0.018 ± 0.003

 (0.457 ± 0.076)

 0.130 ± 0.005 (3.302±0.127)

0.125-0.140

(3.175 - 3.556)

0.092 (2.337) DIA

PIN NO. 1 IDENT

OPTION 1

204

0.065

0.030 (0.762) MAX

0.125 (3.175) DIA NOM

 0.045 ± 0.015 (1.143±0.381) 8 7

OPTION 2

N08E (REV F)

 $\frac{0.032 \pm 0.005}{(0.813 \pm 0.127)}$

PIN NO. 1 IDENT

0.020

(0.508) MIN

RAD

0.145-0.200

(3.683-5.080)

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National Semiconductor

LM675 Power Operational Amplifier

General Description

The LM675 is a monolithic power operational amplifier featuring wide bandwidth and low input offset voltage, making it equally suitable for AC and DC applications.

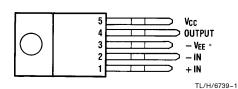
The LM675 is capable of delivering output currents in excess of 3 amps, operating at supply voltages of up to 60V. The device overload protection consists of both internal current limiting and thermal shutdown. The amplifier is also internally compensated for gains of 10 or greater.

Features

- 3A current capability
- A_{VO} typicaly 90 dB
- 5.5 MHz gain bandwidth product
- 8 V/µs slew rate
- Wide power bandwidth 70 kHz

Connection Diagram

TO-220 Power Package (T)



Front View Order Number LM675T See NS Package T05D

*The tab is internally connected to pin 3 ($-\,\mathrm{V_{EE}})$

1 mV typical offset voltage

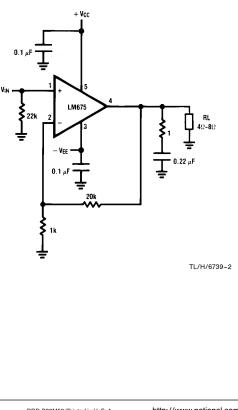
- Short circuit protection
- Thermal protection with parole circuit (100% tested)
- 16V-60V supply range
- Wide common mode range
- Internal output protection diodes
- 90 dB ripple rejection
- Plastic power package TO-220

Applications

- High performance power op amp
- Bridge amplifiers
- Motor speed controls
- Servo amplifiers
- Instrument systems

Typical Applications

Non-Inverting Amplifier



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LM675 Power Operational Amplifier

May 1996

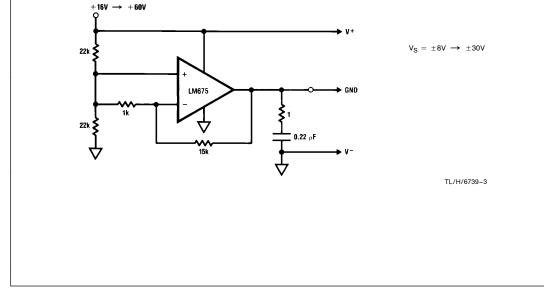
Absolute Maximum Rati If Military/Aerospace specified dev please contact the National Sem Office/Distributors for availability an Supply Voltage Input Voltage	ices are required, hiconductor Sales	Operating Temp Storage Temper Junction Temper Power Dissipatio Lead Temperatu ESD rating to be	ature rature n (Note 1) re (Soldering,	−65°C1	to +70°C to +150°C 150°C 30W 260°C
Electrical Characteristic		0		Tested Limit	Units
Supply Current	P _{OUT} = 0W		18	50 (max)	mA
Input Offset Voltage	$V_{\rm CM} = 0V$		1	10 (max)	mV

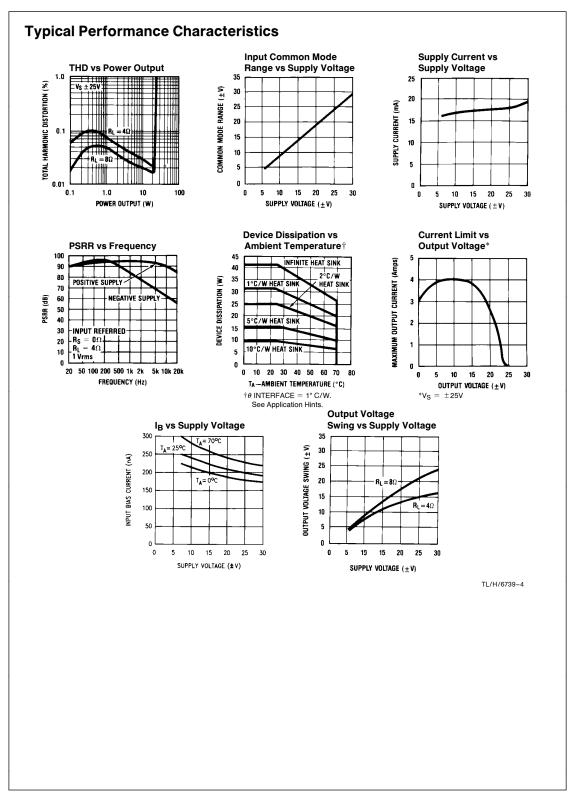
Input Offset Voltage 00 10 (m $V_{CM} = 0V$ Input Bias Current 0.2 2 (max) μA $V_{CM} = 0V$ 50 Input Offset Current 500 (max) nA dB Open Loop Gain $\mathsf{R}_\mathsf{L}=\,\infty\,\Omega$ 90 70 (min) PSRR $\Delta V_{S} = \pm 5V$ dB 90 70 (min) 90 CMRR $V_{\mathsf{IN}}=~\pm\,20V$ dB 70 (min) $\mathsf{R}_\mathsf{L}=\mathsf{8}\Omega$ ±21 ٧ Output Voltage Swing $\pm\,18$ (min) Offset Voltage Drift Versus Temperature $R_S < 100 \ k\Omega$ 25 μV/°C Offset Voltage Drift Versus Output Power 25 μV/W Output Power THD = 1%, f_{O} = 1 kHz, R_{L} = 8Ω 25 W 20 Gain Bandwidth Product $f_{O} = 20 \text{ kHz}, A_{VCL} = 1000$ 5.5 MHz 8 V/µs Max Slew Rate Input Common Mode Range ± 22 \pm 20 (min) ٧

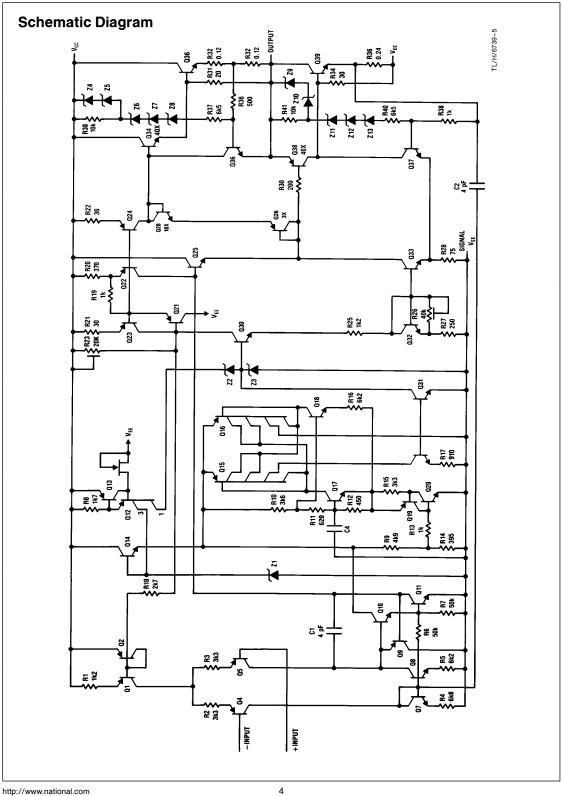
Note 1: Assumes T_A equal to 70°C. For operation at higher tab temperatures, the LM675 must be derated based on a maximum junction temperature of 150°C.

Typical Applications (Continued)

Generating a Split Supply From a Single Supply







Application Hints

STABILITY

The LM675 is designed to be stable when operated at a closed-loop gain of 10 or greater, but, as with any other high-current amplifier, the LM675 can be made to oscillate under certain conditions. These usually involve printed circuit board layout or output/input coupling.

When designing a printed circuit board layout, it is important to return the load ground, the output compensation ground, and the low level (feedback and input) grounds to the circuit board ground point through separate paths. Otherwise, large currents flowing along a ground conductor will generate voltages on the conductor which can effectively act as signals at the input, resulting in high frequency oscillation or excessive distortion. It is advisable to keep the output compensation components and the 0.1 μ F supply decoupling capacitors as close as possible to the LM675 to reduce the effects of PCB trace resistance and inductance. For the same reason, the ground return paths for these components should be as short as possible.

Occasionally, current in the output leads (which function as antennas) can be coupled through the air to the amplifier input, resulting in high-frequency oscillation. This normally happens when the source impedance is high or the input leads are long. The problem can be eliminated by placing a small capacitor (on the order of 50 pF to 500 pF) across the circuit input.

Most power amplifiers do not drive highly capacitive loads well, and the LM675 is no exception. If the output of the LM675 is connected directly to a capacitor with no series resistance, the square wave response will exhibit ringing if the capacitance is greater than about 0.1 μ F. The amplifier can typically drive load capacitances up to 2 μ F or so without oscillating, but this is not recommended. If highly capacitive loads are expected, a resistor (at least 1\Omega) should be placed in series with the output of the LM675. A method commonly employed to protect amplifiers from low impedances at high frequencies is to couple to the load through a 10 Ω resistor in parallel with a 5 μ H inductor.

CURRENT LIMIT AND SAFE OPERATING AREA (SOA) PROTECTION

A power amplifier's output transistors can be damaged by excessive applied voltage, current flow, or power dissipation. The voltage applied to the amplifier is limited by the design of the external power supply, while the maximum current passed by the output devices is usually limited by internal circuitry to some fixed value. Short-term power dissipation is usually not limited in monolithic operational power amplifiers, and this can be a problem when driving reactive loads, which may draw large currents while high voltages appear on the output transistors. The LM675 not only limits current when an output transistor has a high voltage across it.

When driving nonlinear reactive loads such as motors or loudspeakers with built-in protection relays, there is a possibility that an amplifier output will be connected to a load whose terminal voltage may attempt to swing beyond the power supply voltages applied to the amplifier. This can cause degradation of the output transistors or catastrophic failure of the whole circuit. The standard protection for this type of failure mechanism is a pair of diodes connected between the output of the amplifier and the supply rails. These are part of the internal circuitry of the LM675, and needn't be added externally when standard reactive loads are driven.

THERMAL PROTECTION

The LM675 has a sophisticated thermal protection scheme to prevent long-term thermal stress to the device. When the temperature on the die reaches 170°C, the LM675 shuts down. It starts operating again when the die temperature drops to about 145°C, but if the temperature again begins to rise, shutdown will occur at only 150°C. Therefore, the device is allowed to heat up to a relatively high temperature if the fault condition is temporary, but a sustained fault will limit the maximum die temperature to a lower value. This greatly reduces the stresses imposed on the IC by thermal cycling, which in turn improves its reliability under sustained fault conditions. This circuitry is 100% tested without a heat sink.

Since the die temperature is directly dependent upon the heat sink, the heat sink should be chosen for thermal resistance low enough that thermal shutdown will not be reached during normal operaton. Using the best heat sink possible within the cost and space constraints of the system will improve the long-term reliability of any power semiconductor.

POWER DISSIPATION AND HEAT SINKING

The LM675 should always be operated with a heat sink, even though at idle worst case power dissipation will be only 1.8W (30 mA \times 60V) which corresponds to a rise in die temperature of 97°C above ambient assuming $\theta_{jA}=54^{\circ}C/W$ for a TO-220 package. This in itself will not cause the thermal protection circuitry to shut down the amplifier when operating at room temperature, but a mere 0.9W of additional power dissipation will shut the amplifier down since T_J will then increase from 122°C (97°C + 25°C) to 170°C.

In order to determine the appropriate heat sink for a given application, the power dissipation of the LM675 in that application must be known. When the load is resistive, the maximum average power that the IC will be required to dissipate is approximately:

$$\mathsf{P}_{\mathsf{D}\,(\mathsf{MAX})}\approx \frac{\mathsf{V}_{\mathsf{S}}^2}{2\pi^2\mathsf{R}_{\mathsf{L}}}+\,\mathsf{P}_{\mathsf{Q}}$$

where V_S is the total power supply voltage across the LM675, R_L is the load resistance and P_Q is the quiescent power dissipation of the amplifier. The above equation is only an approximation which assumes an "ideal" class B output stage and constant power dissipation in all other parts of the circuit. As an example, if the LM675 is operated on a 50V power supply with a resistive load of 8 Ω , it can develop up to 19W of internal power dissipation. If the die temperature is to remain below 150°C for ambient temperatures up to 70°C, the total junction-to-ambient thermal resistance must be less than

$$\frac{50^{\circ}\text{C} - 70^{\circ}\text{C}}{19\text{W}} = 4.2^{\circ}\text{C/W}.$$

1

Using $\theta_{JC} = 2^{\circ}C/W$, the sum of the case-to-heat sink interface thermal resistance and the heat-sink-to-ambient

Application Hints (Continued)

thermal resistance must be less than 2.2°C/W. The case-to-heat-sink thermal resistance of the TO-220 package varies with the mounting method used. A metal-to-metal interface will be about 1°C/W if lubricated, and about 1.2°C/W if dry. If a mica insulator is used, the thermal resistance will be about 1.6°C/W lubricated and 3.4°C/W dry. For this example, we assume a lubricated mica insulator between the LM675 and the heat sink. The heat sink thermal resistance must then be less than

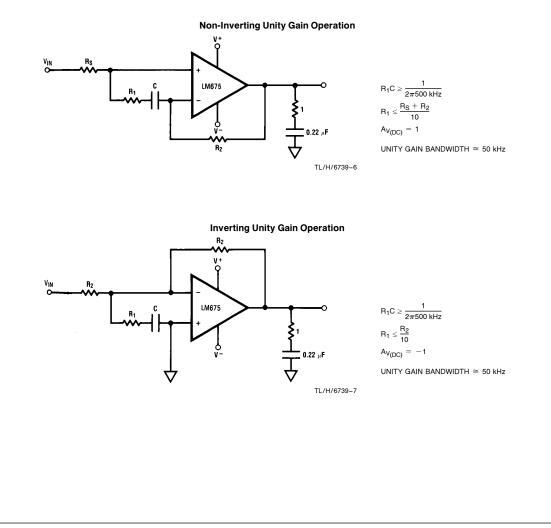
 $4.2^{\circ}C/W - 2^{\circ}C/W - 1.6^{\circ}C/W = 0.6^{\circ}C/W.$

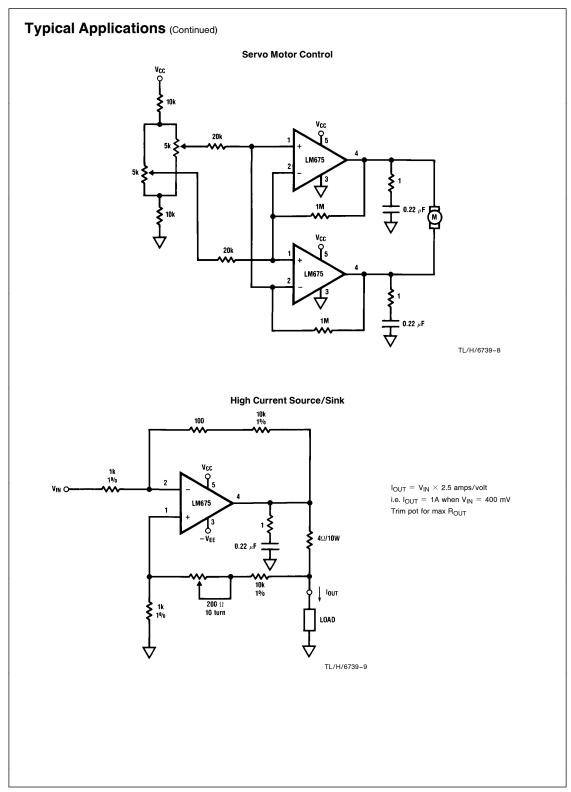
This is a rather large heat sink and may not be practical in some applications. If a smaller heat sink is required for reasons of size or cost, there are two alternatives. The maximum ambient operating temperature can be restricted to $50^{\circ}C$ (122°F), resulting in a 1.6°C/W heat sink, or the heat

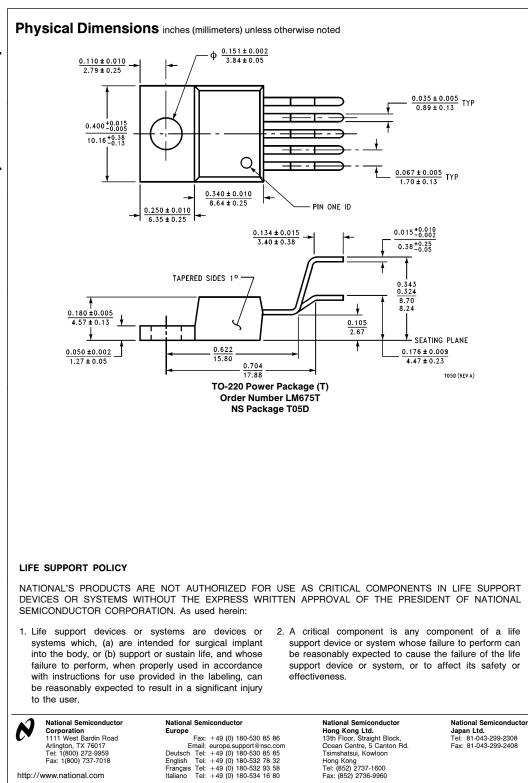
Typical Applications (Continued)

sink can be isolated from the chassis so the mica washer is not needed. This will change the required heat sink to a 1.2°C/W unit if the case-to-heat-sink interface is lubricated. The thermal requirements can become more difficult when an amplifier is driving a reactive load. For a given magnitude of load impedance, a higher degree of reactance will cause a higher level of power dissipation of an amplifier As a general rule, the power dissipation of an amplifier driving a 60° reactive load will be roughly that of the same amplifier driving the resistive part of that load. For example, some reactive loads may at some frequency have an impedance with a magnitude of 8 Ω and a phase angle of 60°. The real part of this load will then be $8\Omega \times \cos 60^\circ$ or 4Ω , and the amplifier power dissipation will roughly follow the curve of

power dissipation with a 4Ω load.







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